

21 Sub C1
1. (Amended) A device enclosure comprising:
a chassis; and
a detachable thermo-siphon device formed as an integral part of a wall of
the chassis.

2. The device of claim 1, wherein the device is an electronic device.
3. The device of claim 2, wherein the device enclosure is a computer chassis.
4. The device of claim 1, wherein the device is a non-electronic device.
5. The device of claim 1, wherein the thermo-siphon device is a heat pipe.
6. The device of claim 1, wherein the thermo-siphon device is a strip of a high efficiency conduit material.
9. The device of claim 1, wherein the wall is fabricated from a metallic material.
10. The device of claim 1, wherein the thermo-siphon device is embedded in a cavity of the wall.
11. The device of claim 10, wherein the cavity is created during a fabrication process of the wall.
12. The device of claim 1, wherein the wall partially encloses the thermo-siphon device.

13. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

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17. (Amended) The device of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the wall cavity.

18. The device of claim 1, wherein a metallic plate interfaces a heat source with the thermo-siphon device.

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19. (Amended) A system comprising:
a chassis; and
a detachable thermo-siphon device formed as an integral part of a wall of the chassis.

20. The system of claim 19, wherein the thermo-siphon device is a heat pipe.

21. The system of claim 19, wherein the thermo-siphon device is a strip of high efficiency conduit material.

22. The system of claim 19, wherein the chassis is a computer chassis.

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24. (Amended) A computer chassis comprising:

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Sub C1~~ a chassis; and

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Sub C1~~ a detachable thermo-siphon device formed as an integral part of a wall of the chassis.

25. The computer chassis of claim 24, wherein the thermo-siphon device is a heat pipe.

26. The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

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Sub C1~~ 28. (Amended) The computer chassis of claim 24, wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.
